

# Distributed Sniffer Nodes for Batteryless Sensor Nodes (sdmay24-25)

Website



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**Hardware Lead:** Tori Kittleson  
**Hardware Member:** Matthew Crabb  
**Software Member:** Spencer Sutton  
**Scribe/Software Member:** Ian Hollingworth

**Advisor/Client:** Henry Duwe  
CPRE/EE 492 Spring 2024

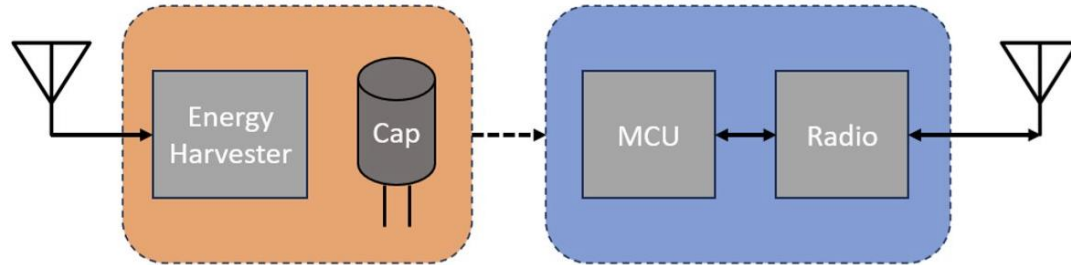
<https://sdmay24-25.sd.ece.iastate.edu/>

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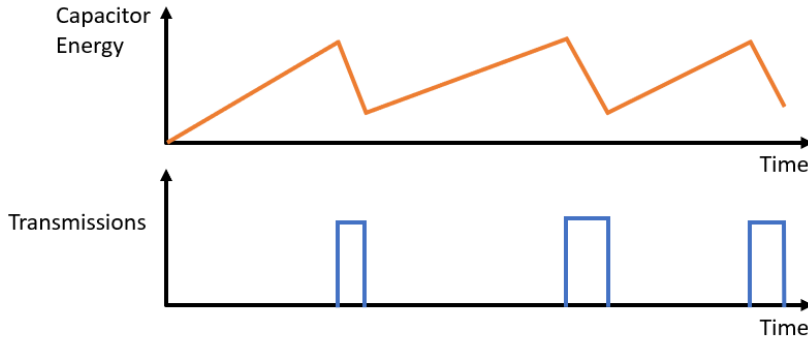
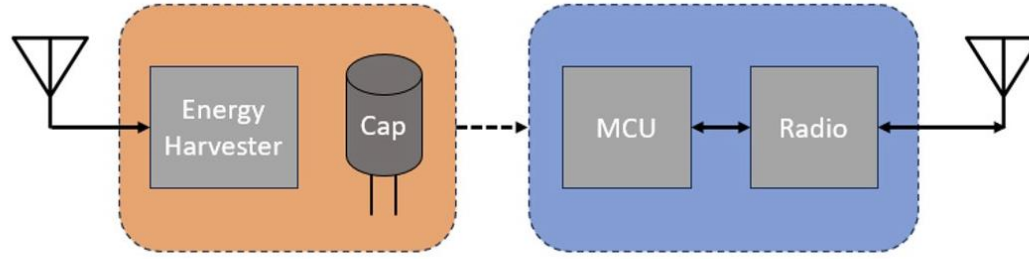
# Project Overview

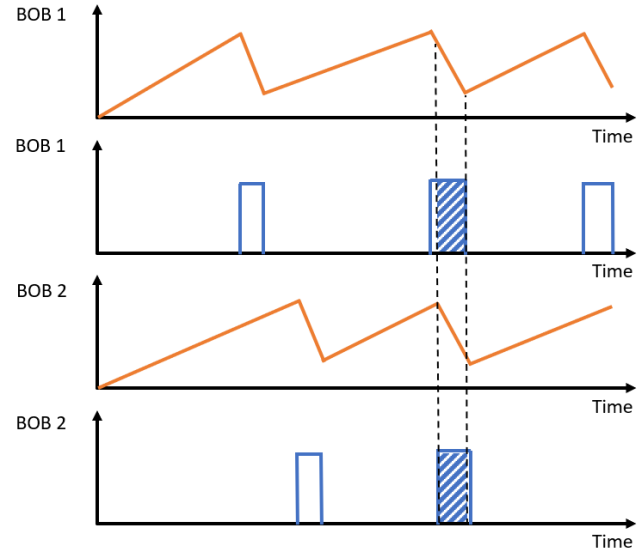
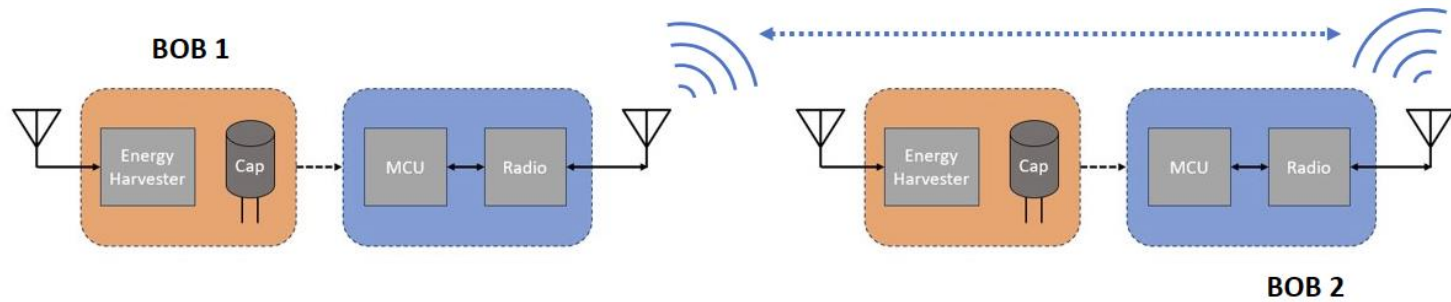
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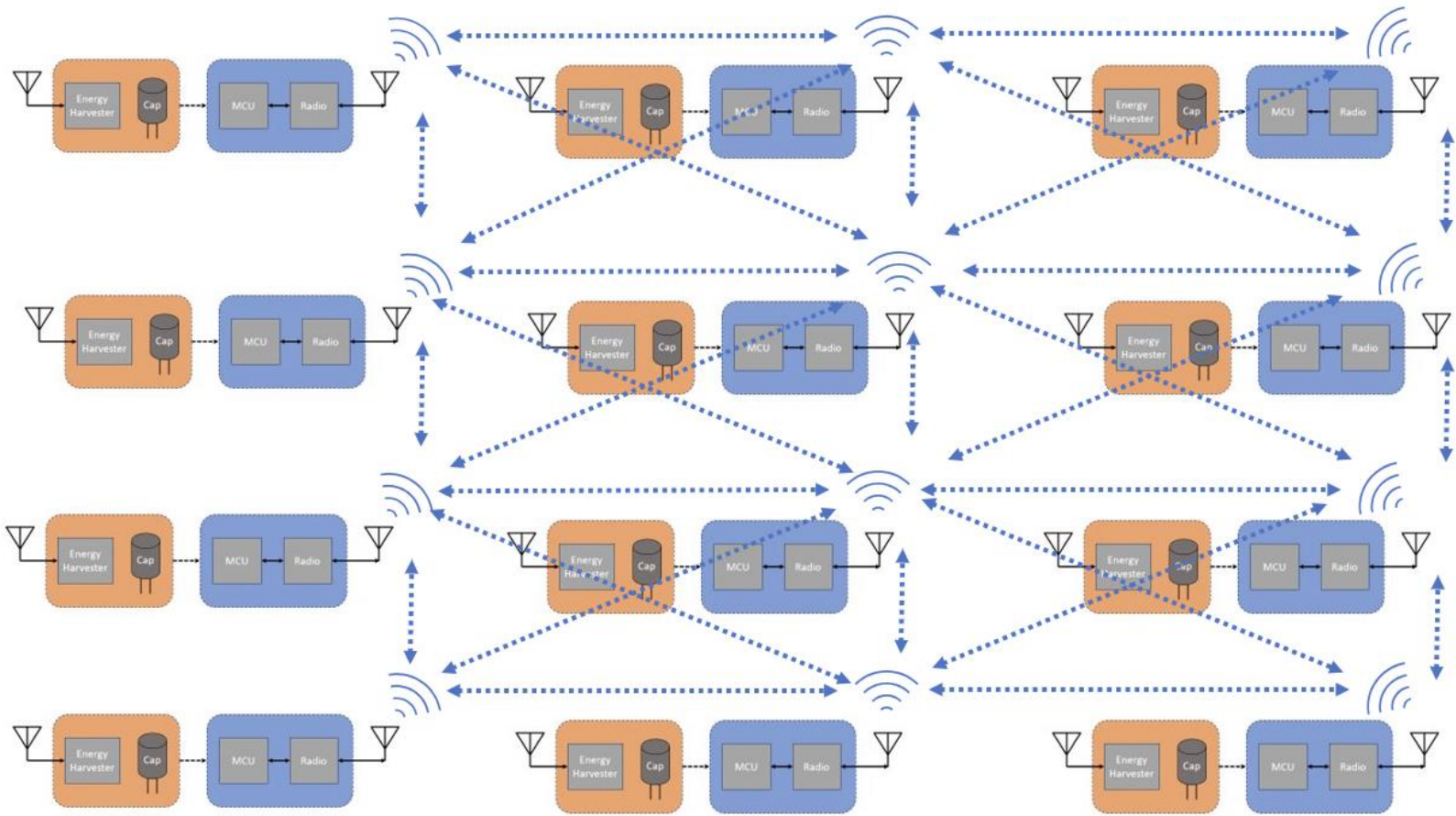
**BOB Node** - Batteryless sensor designed by client.



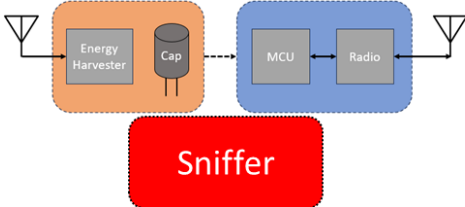
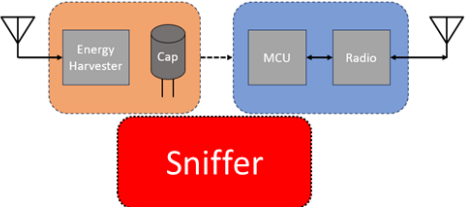
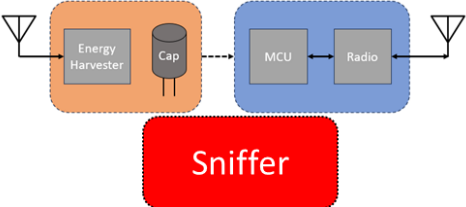
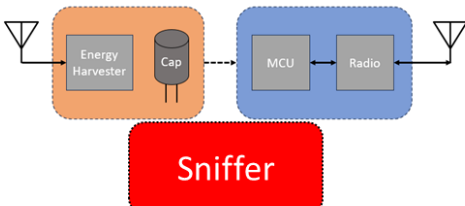
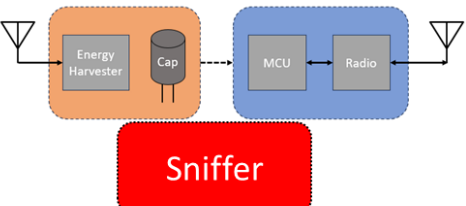
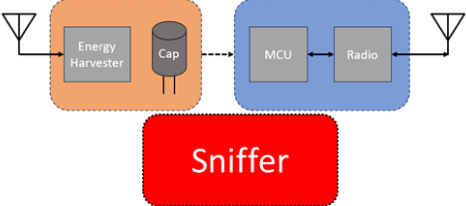
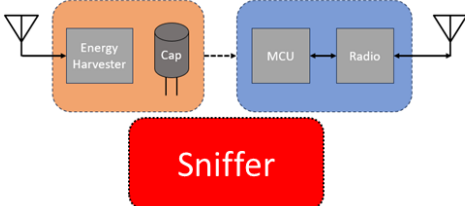
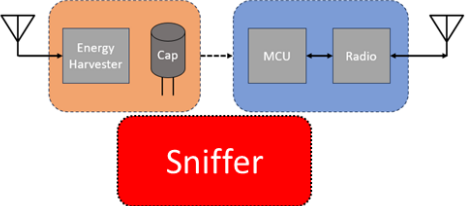
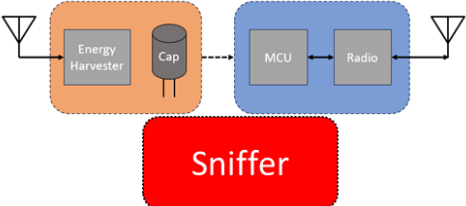
# Project Overview







**Goal:** Create testbed for researchers to use for the batteryless nodes they are developing.



# Use Cases

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## Scenario Node Tests

- Single node tests
- Multi-node and single lab testing (goal of 9)
- Large scale testing (goal of 100 – 1000)

## Users

- Dr. Duwe's research group
- Universities, companies, hobbyists through open-source nature

## Potential Impact

- Forest fire detection in national parks
- Factory condition monitoring
- Weather monitoring and recording

# Requirements

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## Functional

- 9 BOB/Sniffer pairs
- Sink Sniffer Node with continuous power
- Host system to organize and store Sniffer logs
- Sniffer Nodes powered for one week
- Sniffer Nodes inflict minimal effects on BOB Nodes
- BOB Nodes electrically isolated from one another
- Modular stack of BOB and Sniffer custom boards

## Non-functional

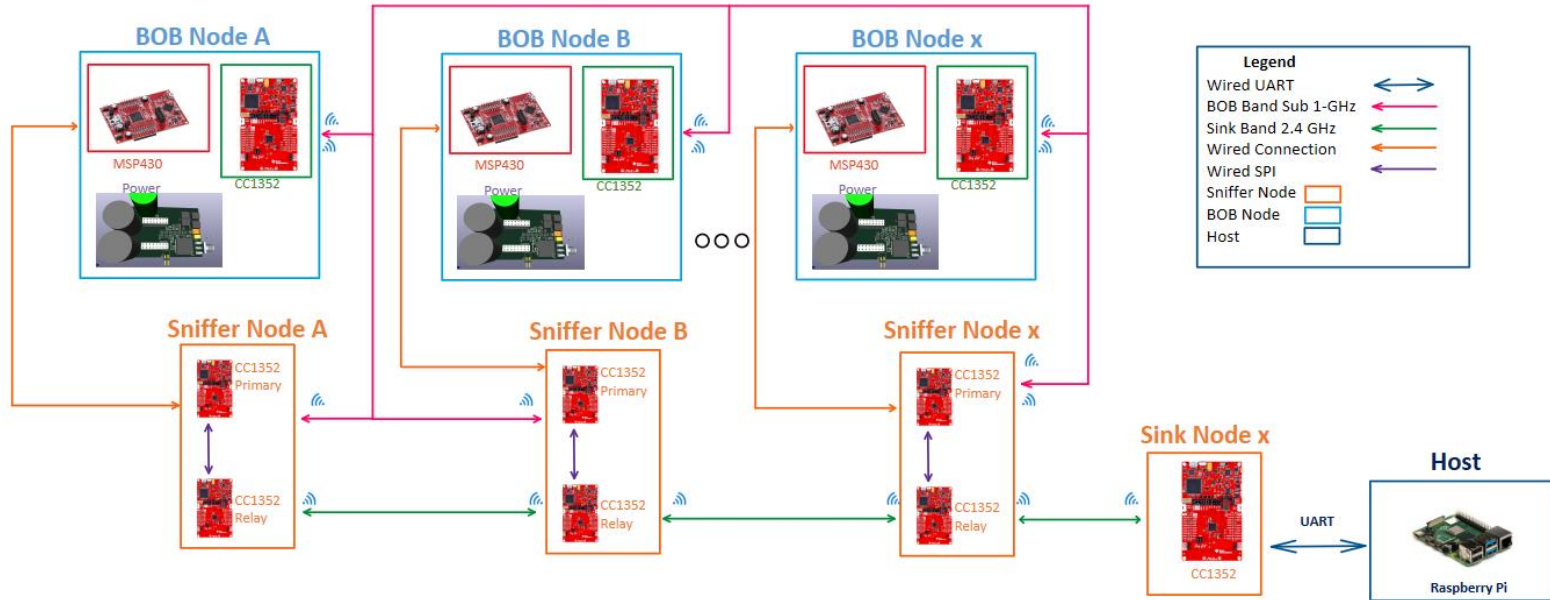
- Scalable for a potential larger (100+ node) design
- Documentation
- Mechanical durability of system

## Deliverables

- Breakout Board Hardware
- MSP Simplified Hardware
- Sniffer Node Hardware
- Sniffer Node Software
- Open-Source Documentation
- Mechanically Sound System



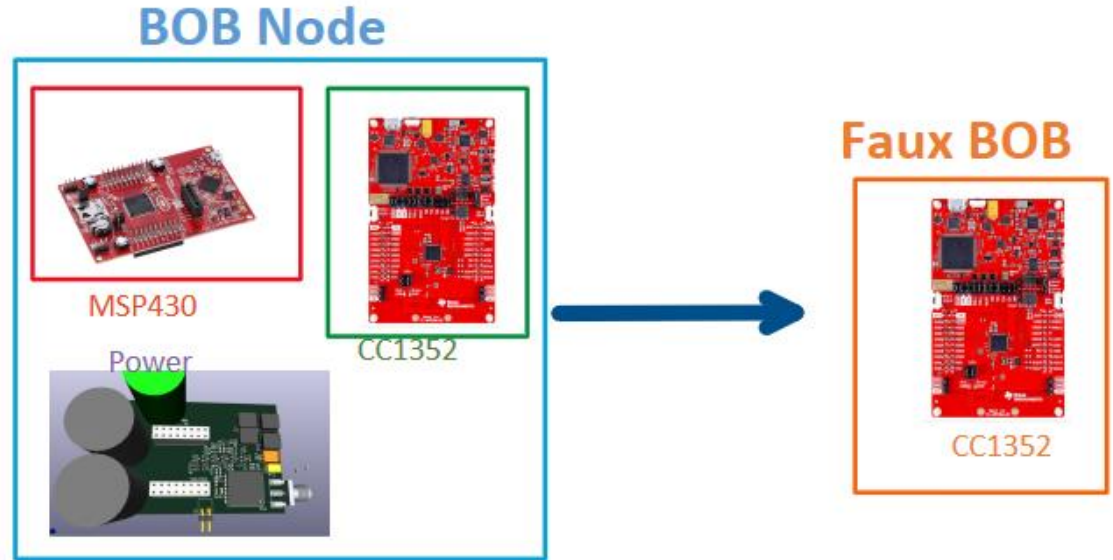
# System Design



# Work Progress: Faux BOB

## Goal

- Create a test tool
- Emulate BOB functionality
- Allows us to have a know test



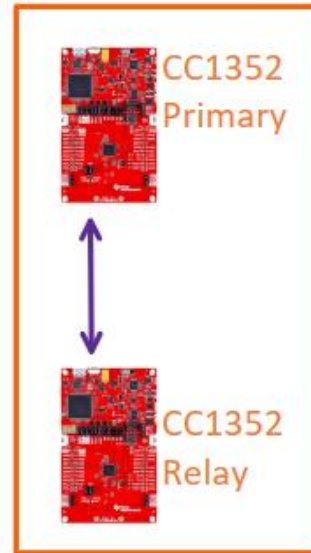
# Work Progress: SPI interface

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## Goal

- Create interface for communicating between two CC1352s
- Allows us to take data from Band (2.4 GHz) and send it to Sub-1 GHz and vice versa

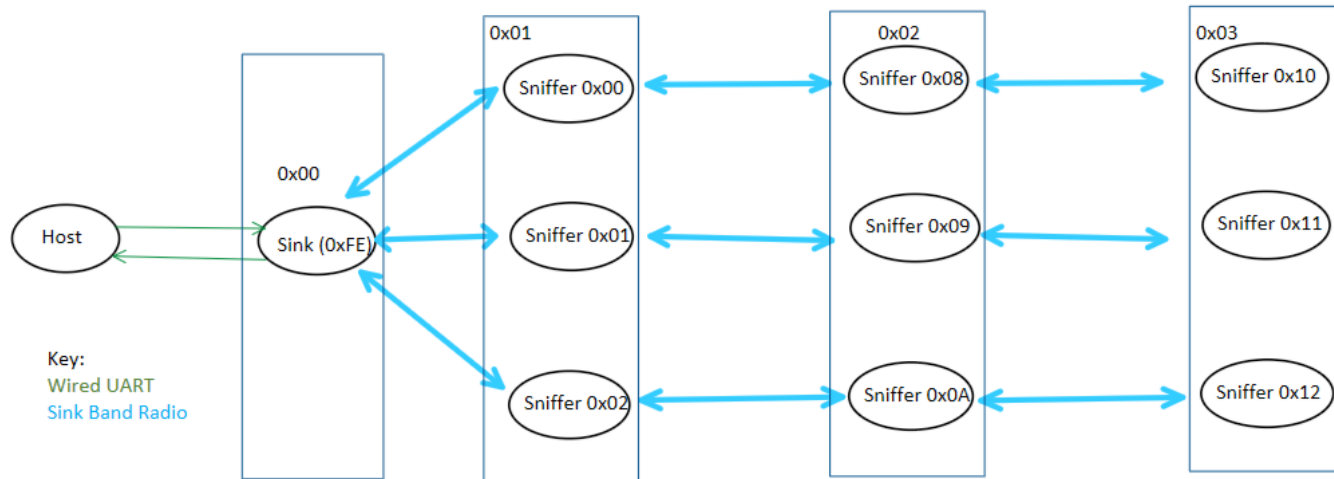
## Sniffer Node



# Work Progress: Software Network

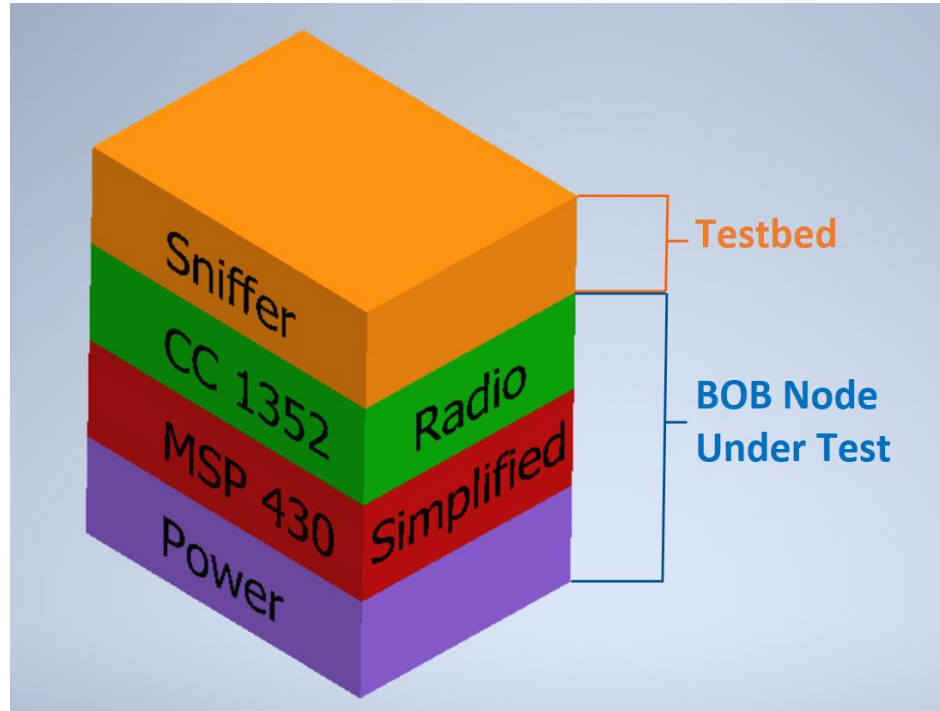
Depth Parameter  
Depth =  $\lfloor \text{Destination Address} / 8 \rfloor + 1$   
Transmit to all is 0xFF  
Transmit to Sink 0xF  
From Sink Node knows path by doing  
Destination % 8

Each destination is 1 byte meaning maximum of 255 destinations in the network (could be increased but due to address filtering in the BOBs this would be unnecessary unless that BOB code changes)

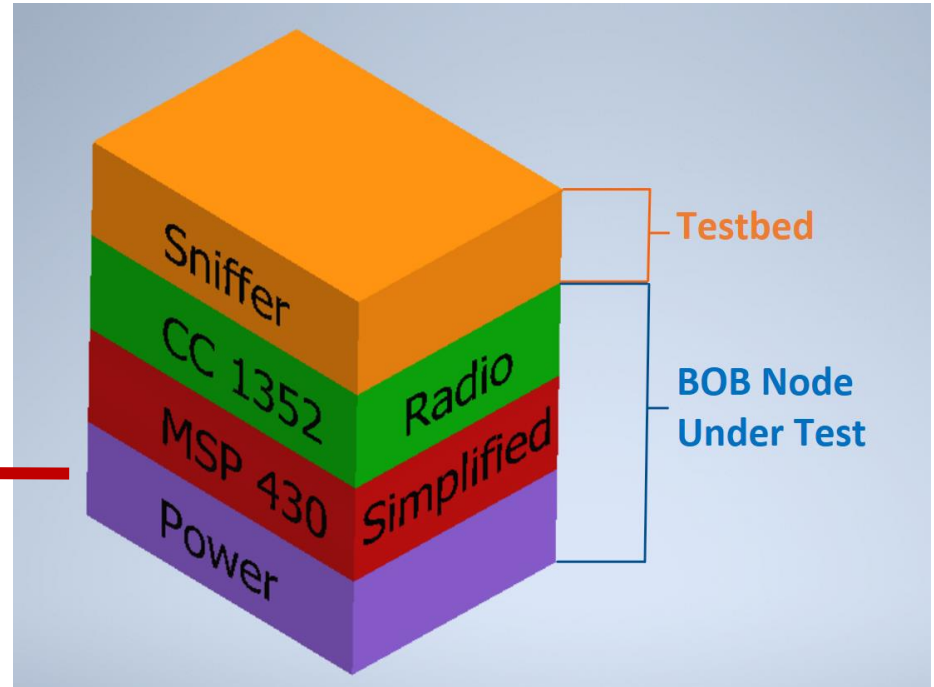
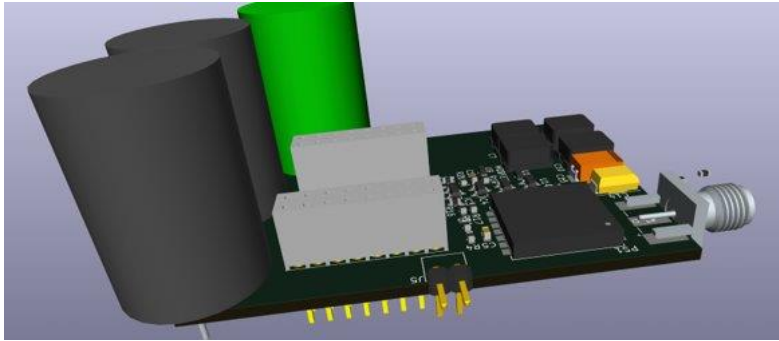


# System Physical Design

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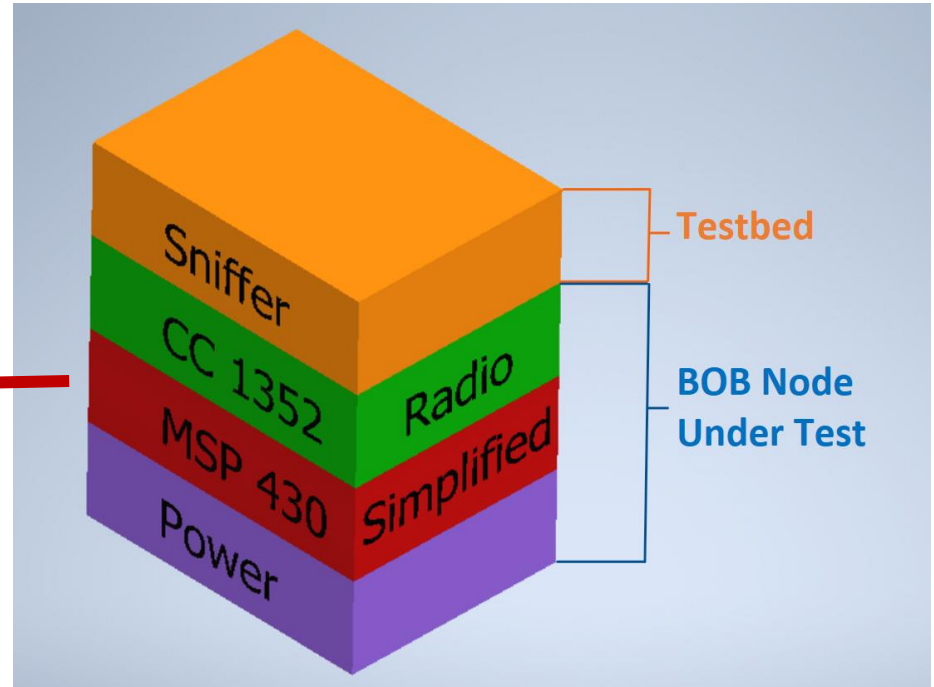
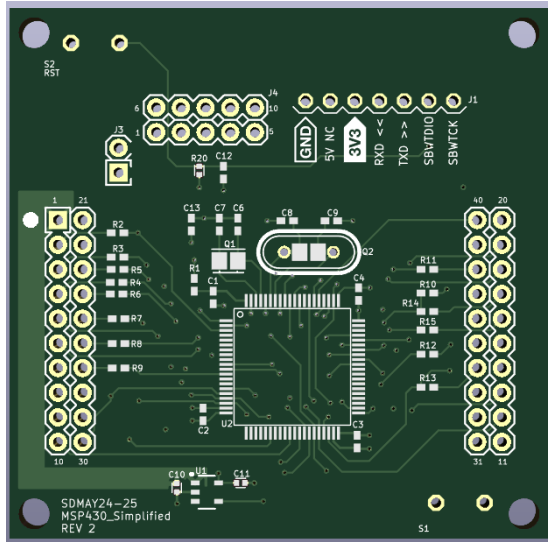


# System Physical Design

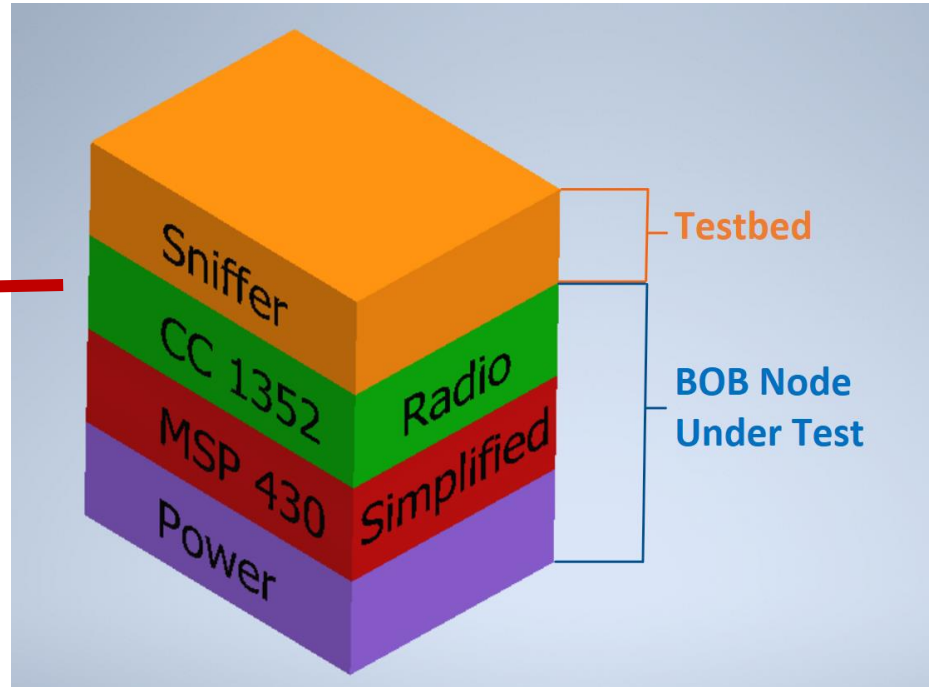
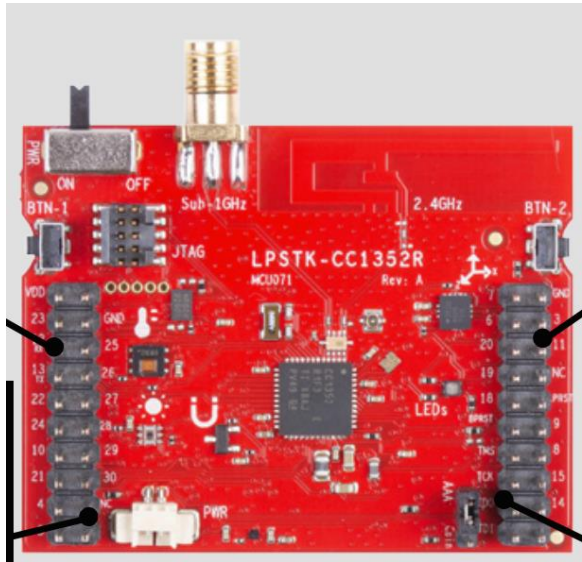


p. 27

# System Physical Design



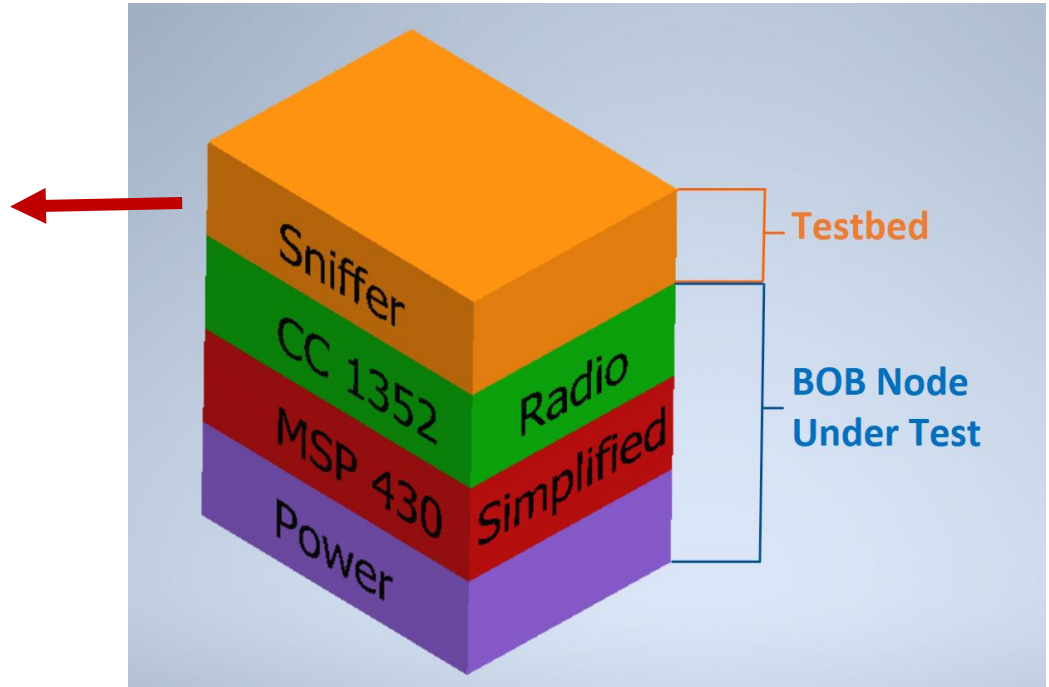
# System Physical Design

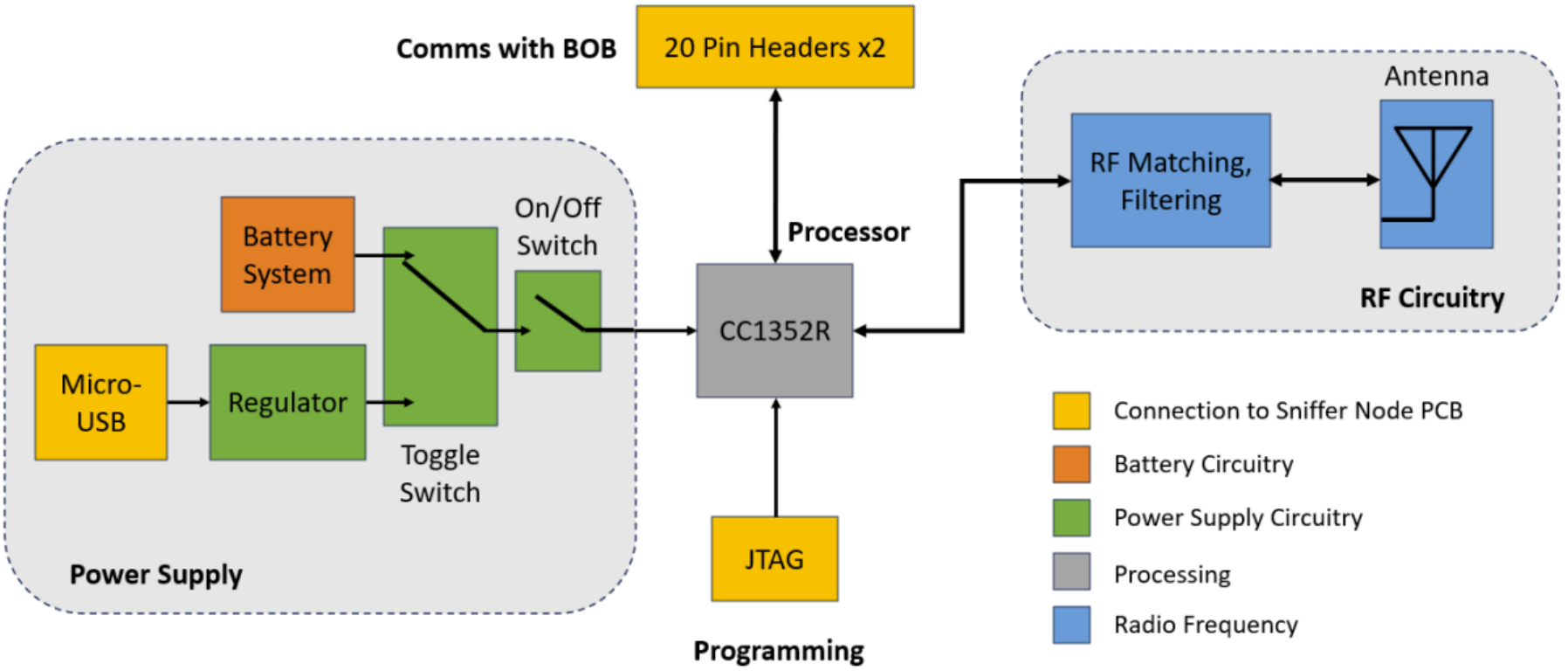


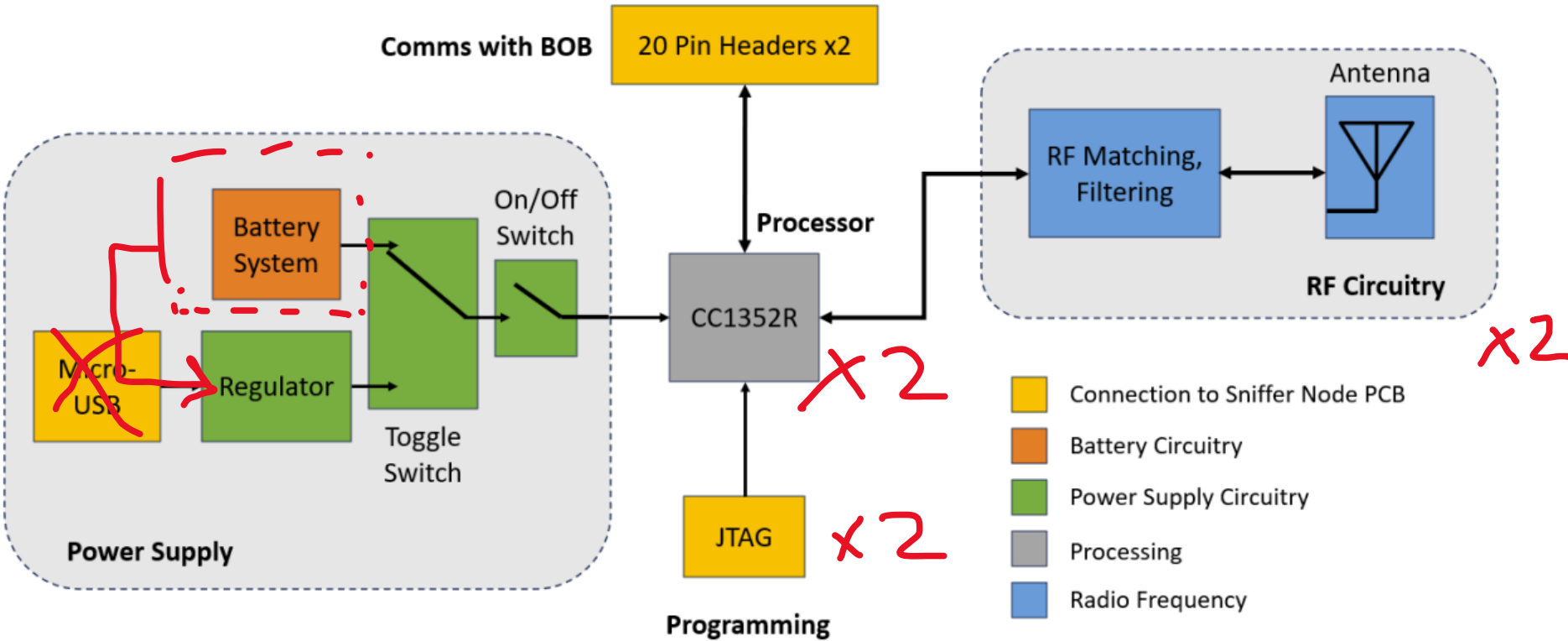


# System Physical Design

Our Design

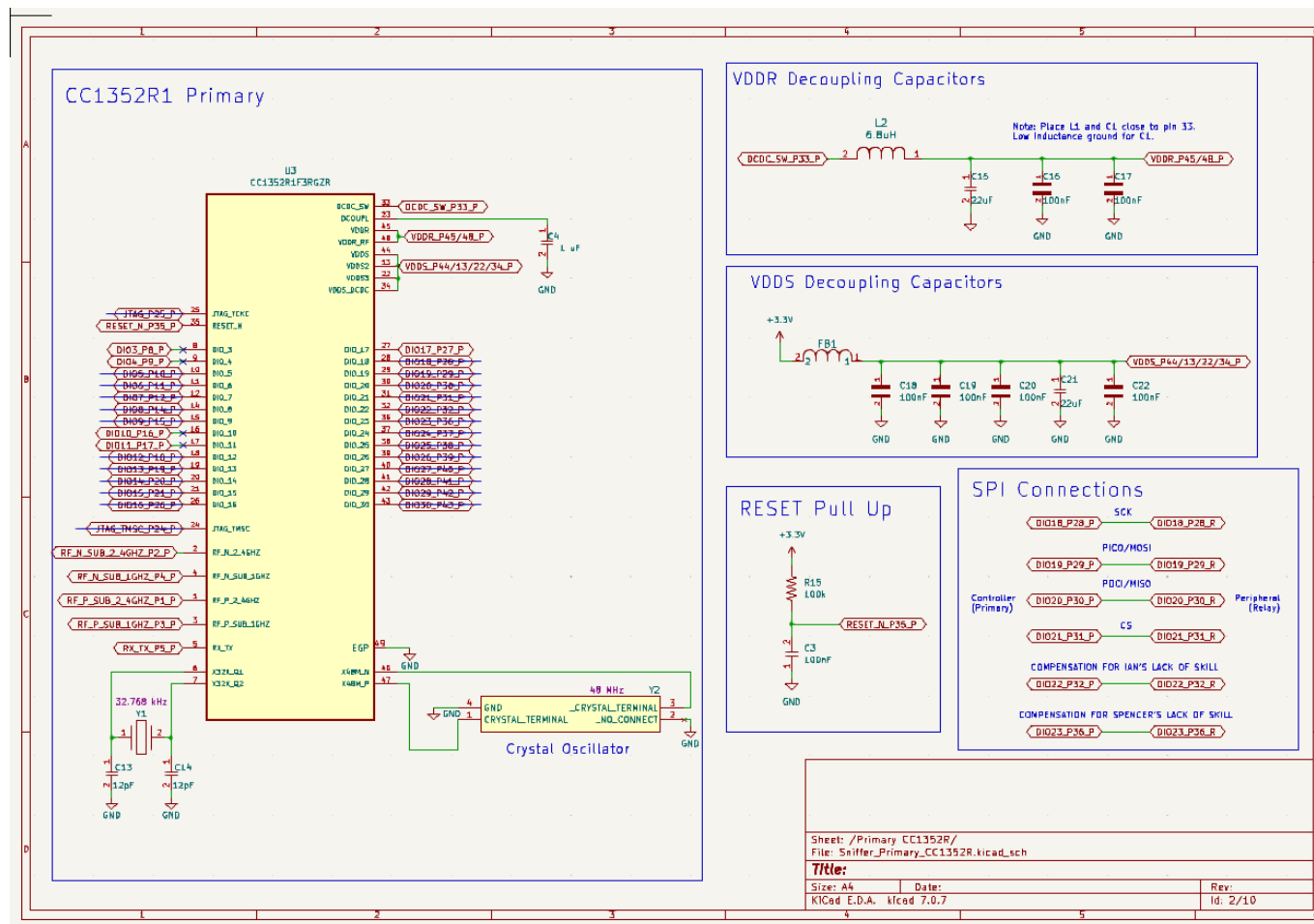


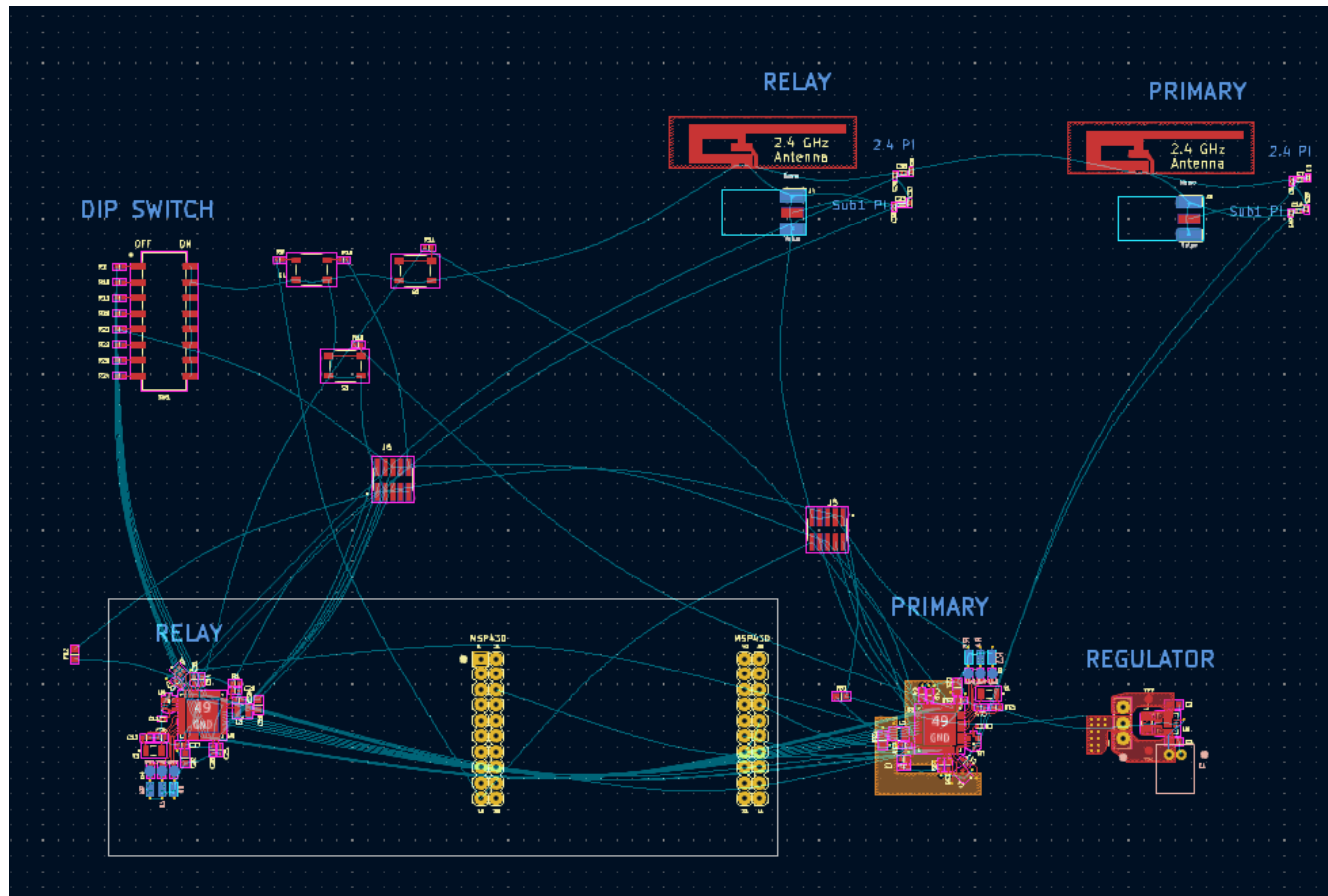




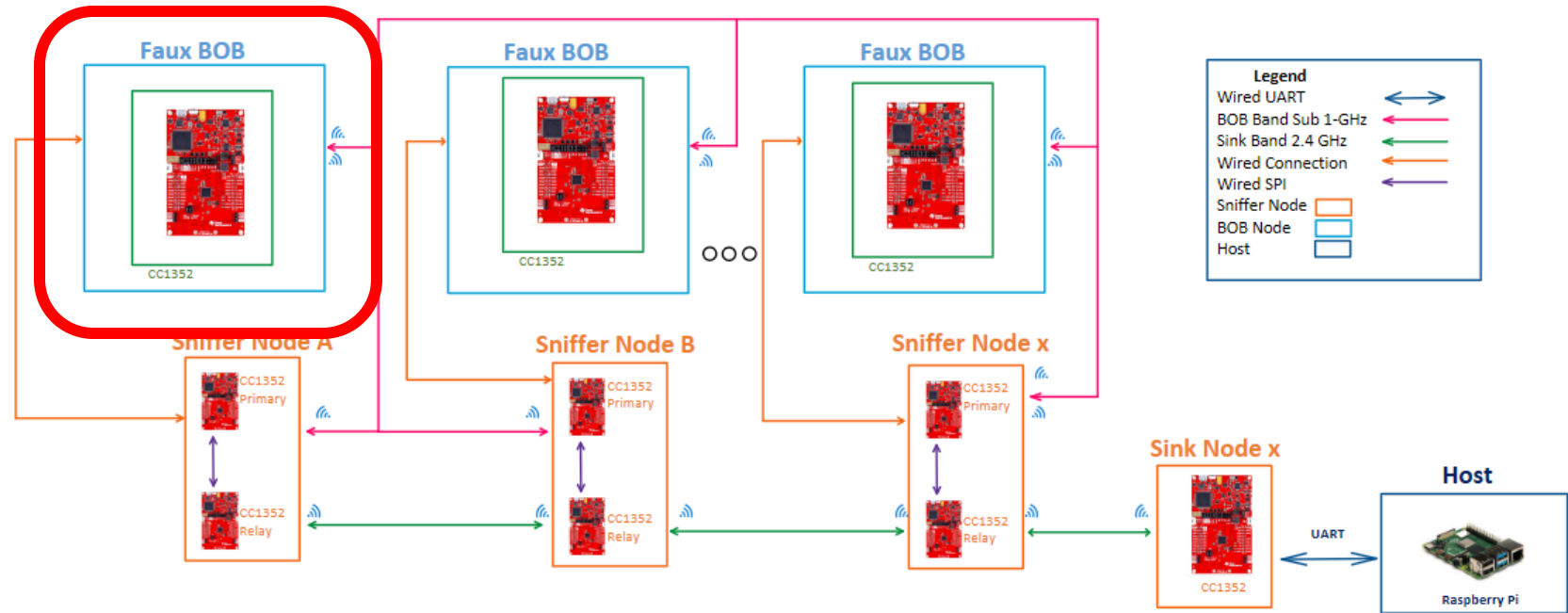
## Our Design Phase:

- Schematic reviewed
- Layout In Prog

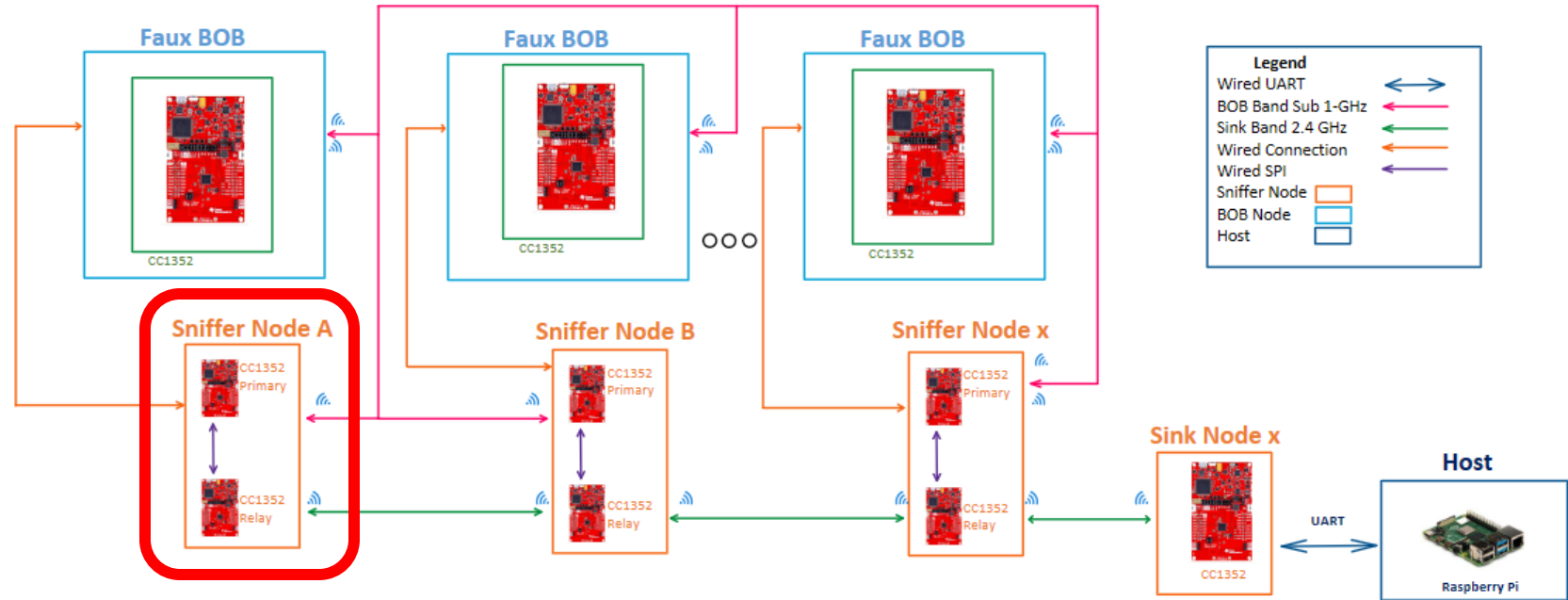




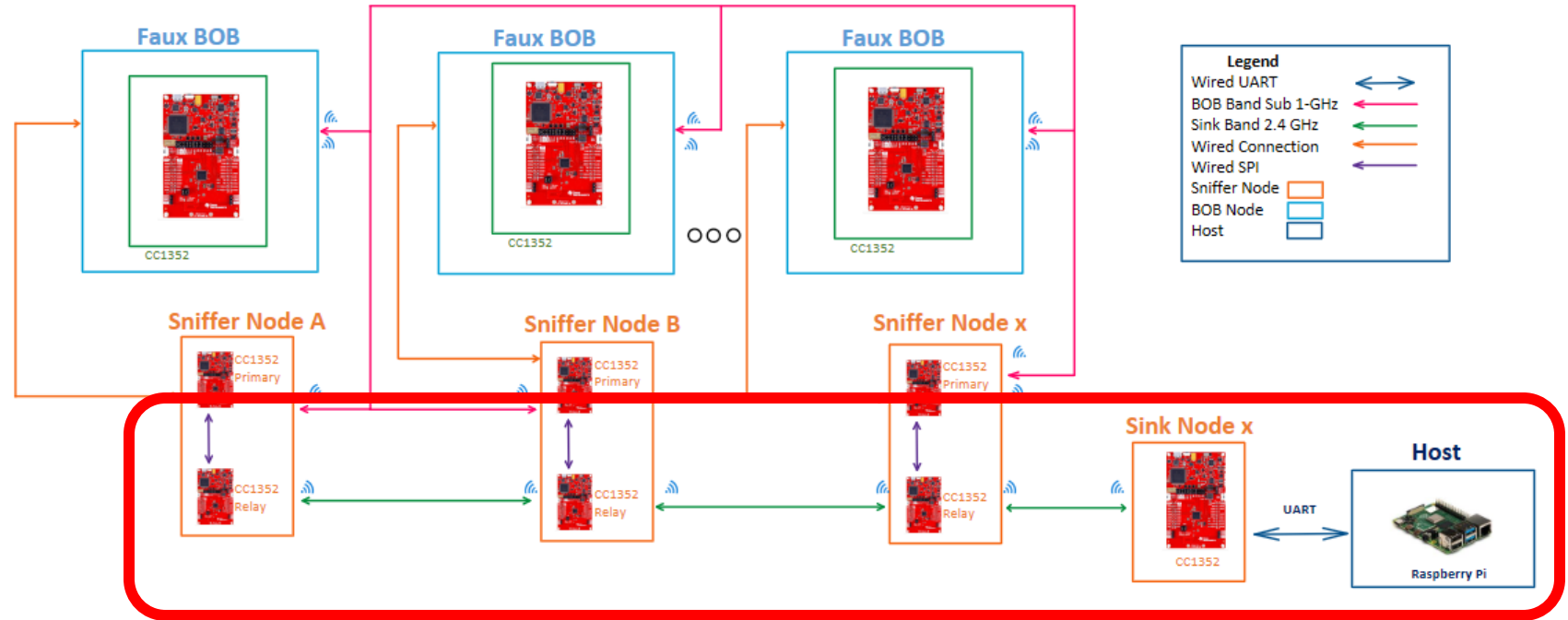
# Current Software Walk-through



# Current Software Walk-through

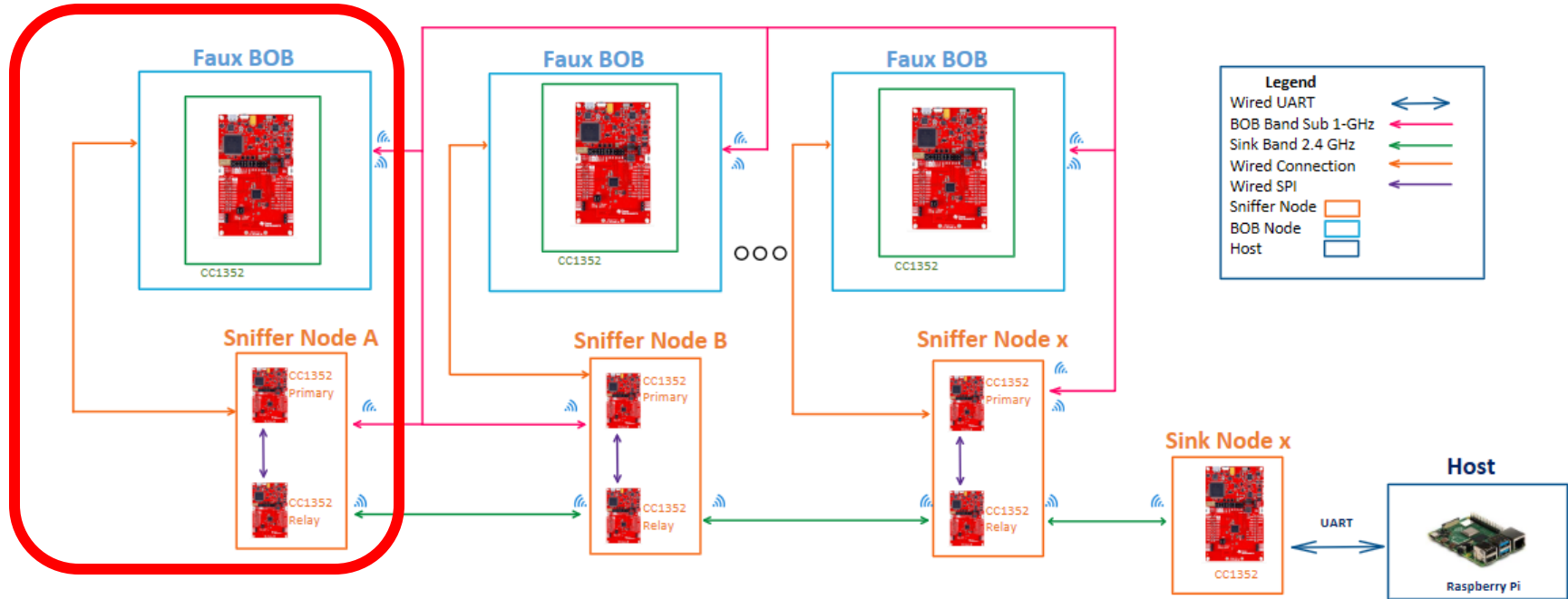


# Current Software Walk-through

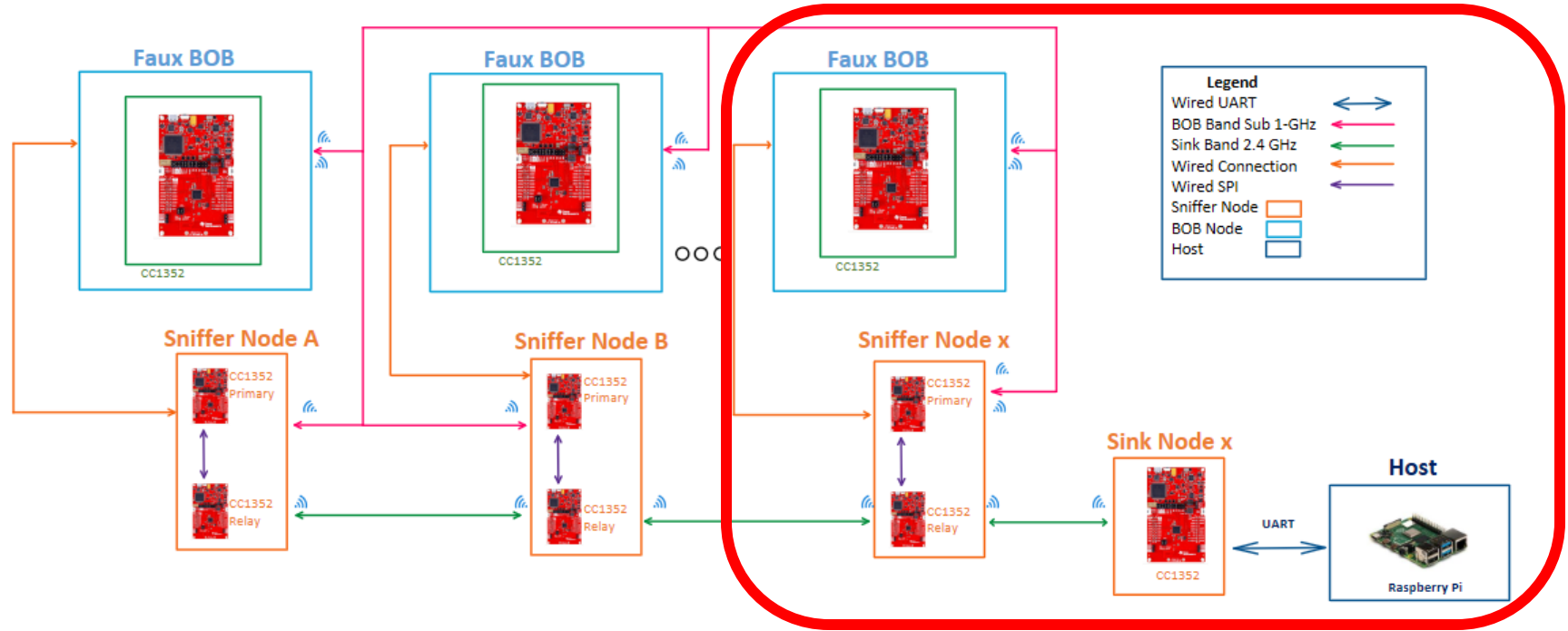




# Next Step Software Walk-through

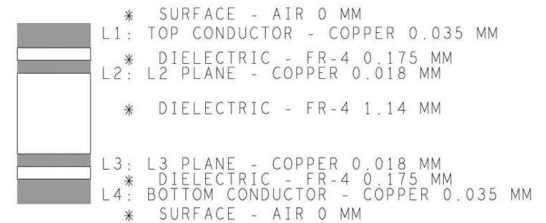


# Next Steps ~90% complete



# Hardware Challenges and Solutions

- Requirement Modifications
- Second Revision of a PCB (layout mistake)
- Worked with client to discuss and fine tune requirements
- Reworked PCB for a second order
- Revised the Gantt chart to update for current progress
- PCB Delays – symbols, footprints, small details



DESIGN CROSS SECTION CHART  
TOTAL THICKNESS 1.6 MM +/- 0.16 MM

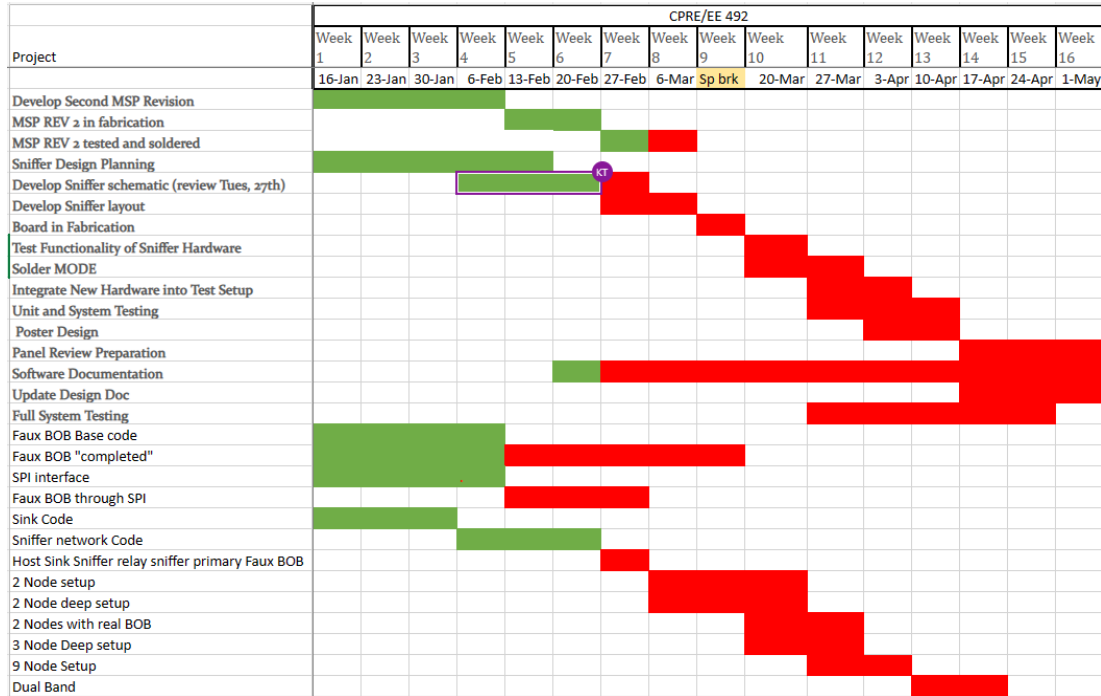
Figure 4-1. CC1312R Board Stack Up

# Software Challenges and Solutions

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- SPI integration
- Talked to people who previously implemented it
- Poor documentation/Weird Quirks of Software
- Got help from experienced individuals
- Divided up unknowns and shared knowledge

# Project Plan – Schedule/Milestones





**Thank you!**

# Hardware Cost Estimates

Cost for Single Board										
Item #	Designator	Manufacturer	Mfg Part #	Description / Value	Package	Supplier	Link	Qty	Cost	Total Cost
1	U1	GLF Integrated Power	GLF1111	Power Switch/Driver P-Channel 2A	SOT-23-5L	DigiKey	<a href="https://www.digikey.com/product-detail/en/4002/4002-ND">https://www.digikey.com/product-detail/en/4002/4002-ND</a>	1	0.33	0.33
2	C1, C2	Samsung Electro-Mechanics	CLO5A104KA5N9NC	CAP CER 0.1UF 25V X5R 0402	0402	DigiKey	<a href="https://www.digikey.com/product-detail/en/4002/4002-ND">https://www.digikey.com/product-detail/en/4002/4002-ND</a>	2	0.01	0.02
3	J1	Samtec Inc.	SSW-110-03-G-D	CONN RCPT 20POS 0.1 GOLD PCB	-	DigiKey	<a href="https://www.digikey.com/product-detail/en/4002/4002-ND">https://www.digikey.com/product-detail/en/4002/4002-ND</a>	2	3.89	7.78
4	J2	Molex	22122024	TH, Right Angle 2 position 0.100" (2.54mm)	-	DigiKey	<a href="https://www.digikey.com/product-detail/en/4002/4002-ND">https://www.digikey.com/product-detail/en/4002/4002-ND</a>	1	0.77	0.77
5	R1	Stackpole Electronics	RMCF0805ZTOR00	RES 0 OHM JUMPER 1/8W 0805	0805	DigiKey	<a href="https://www.digikey.com/product-detail/en/4002/4002-ND">https://www.digikey.com/product-detail/en/4002/4002-ND</a>	1	0.018	0.018
6	-	-	-	Board Fabrication	-	JLPCPB	-	1	3.892	3.892
									<b>Total Cost</b>	<b>12.48</b>

## Cost Per Breakout Board

Cost for single board										
Item #	Designator	Manufacturer	Mfg Part #	Description / Value	Package	Supplier	Link	Qty	Cost	Total Cost
1	U1	GLF Integrated Power	GLF1111	Power Switch/Driver P-Channel 2A	SOT-23-5L	DigiKey	<a href="https://www.digikey.com/product-detail/en/4002/4002-ND">https://www.digikey.com/product-detail/en/4002/4002-ND</a>	1	0.33	0.33
2	C1, C2, C3, C4, C10, C11	TDK Corporation	C1005X5R1A104M050B	CAP CER 0.1UF 10V X5R 0402	0402	DigiKey	<a href="https://www.digikey.com/product-detail/en/4002/4002-ND">https://www.digikey.com/product-detail/en/4002/4002-ND</a>	6	0.021	0.126
3	J2	Samtec Inc.	SSW-110-03-G-D	CONN RCPT 20POS 0.1 GOLD PCB	-	DigiKey	<a href="https://www.digikey.com/product-detail/en/4002/4002-ND">https://www.digikey.com/product-detail/en/4002/4002-ND</a>	2	3.89	7.78
4	J3	Molex	22122024	TH, Right Angle 2 position 0.100" (2.54mm)	-	DigiKey	<a href="https://www.digikey.com/product-detail/en/4002/4002-ND">https://www.digikey.com/product-detail/en/4002/4002-ND</a>	1	0.64	0.64
5	C6, C7	TDK Corporation	C1005C0G1H220J050BA	CAP CER 22PF 50V COG 0402	0402	DigiKey	<a href="https://www.digikey.com/product-detail/en/4002/4002-ND">https://www.digikey.com/product-detail/en/4002/4002-ND</a>	2	0.047	0.094
6	C12	TDK Corporation	C1005X7R1H102K050BA	CAP CER 1000PF 50V X7R 0402	0402	DigiKey	<a href="https://www.digikey.com/product-detail/en/4002/4002-ND">https://www.digikey.com/product-detail/en/4002/4002-ND</a>	1	0.051	0.051
7	C13	Murata Electronics	GRM155R61A106ME11E	CAP CER 10UF 10V X5R 0402	0402	DigiKey	<a href="https://www.digikey.com/product-detail/en/4002/4002-ND">https://www.digikey.com/product-detail/en/4002/4002-ND</a>	1	0.091	0.091
8	J1	Sullins Connector Solutions	PRPC0075BAN-M71RC	CONN HEADER R/A 7POS 2.54MM	-	DigiKey	<a href="https://www.digikey.com/product-detail/en/4002/4002-ND">https://www.digikey.com/product-detail/en/4002/4002-ND</a>	1	0.191	0.191
9	Q1	EPSON	FC-135R 32.7680KA-A0	CRYSTAL 32.7680KHZ 12.5PF SMD	-	DigiKey	<a href="https://www.digikey.com/product-detail/en/4002/4002-ND">https://www.digikey.com/product-detail/en/4002/4002-ND</a>	1	0.7	0.7
10	R1, R2, R3, R4, R5, R6, R7	YAGEO	RC0402JR-070RL	RES 0 OHM JUMPER 1/16W 0402	0402	DigiKey	<a href="https://www.digikey.com/product-detail/en/4002/4002-ND">https://www.digikey.com/product-detail/en/4002/4002-ND</a>	17	0.0045	0.0765
11	R18	YAGEO	RC0402FR-0747KL	RES 47K OHM 1% 1/16W 0402	0402	DigiKey	<a href="https://www.digikey.com/product-detail/en/4002/4002-ND">https://www.digikey.com/product-detail/en/4002/4002-ND</a>	1	0.015	0.015
12	U2	Texas Instruments	MSP430FR5994IPN	IC MCU 16BIT 256KB FRAM 80LQFP	-	Mouser	<a href="https://www.digikey.com/product-detail/en/4002/4002-ND">https://www.digikey.com/product-detail/en/4002/4002-ND</a>	1	11.27	11.27
13	Q2	DNP	-	-	-	-	-	-	-	-
14	-	Würth Elektronik	60900213421	JUMPER W/TACT PNT 1X2PINS 2.54MM	-	DigiKey	<a href="https://www.digikey.com/product-detail/en/4002/4002-ND">https://www.digikey.com/product-detail/en/4002/4002-ND</a>	1	0.31	0.31
15	S1,S2	E-Switch	TL59NF160Q	SWITCH TACTILE SPST-NO 0.05A 12V	-	DigiKey	<a href="https://www.digikey.com/product-detail/en/4002/4002-ND">https://www.digikey.com/product-detail/en/4002/4002-ND</a>	2	0.284	0.568
16	J2 (trying another comp)	Samtec Inc.	SSW-110-23-G-D	CONN RCPT 20POS 0.1 GOLD PCB	-	DigiKey	<a href="https://www.digikey.com/product-detail/en/4002/4002-ND">https://www.digikey.com/product-detail/en/4002/4002-ND</a>	0	5.71	0
17	-	-	-	PCB Fabrication	-	JLPCPB	-	1	4.96	4.96
									<b>Total Cost</b>	<b>27.2025</b>

## Cost Per MSP Simplified Single Board Cost

Approximate Cost Per Board	
Breakout Board	~\$13
MSP Simplified	~\$28

## Literature Study

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- "Experimental Study of Lifecycle Management Protocols for Batteryless Intermittent Communication"[2]
- "Toward a Shared Sense of Time for a Network of Batteryless, Intermittently-powered Nodes"[3]
- "Reliable Timekeeping for Intermittent Computing"[4]



# Stack Pinouts

**SD)**

Table 1				Table 2					
GPIO	MSP430	CC1352 radio	I/O (as seen from the msp430)	GPIO	MSP430	CC1352 radio	CC1352 sniffer	Harvester	I/O
Data Received	P5.0	DIO22	I	Powered ON	P7.7		DIO25	DIO28	O
Transmit Request	P5.1	DIO3	O	Event Gen	P7.4		DIO26	DIO29	I
Transmit Done	P5.2	DIO24	I	Testbed Reset	P7.5		DIO27	DIO30	I
SPI Master Ready	P5.3	DIO19	O	Easylink Tx		DIO25	DIO24	DIO21	
SPI Slave Ready	P5.4	DIO7	I	Event drop	P7.6		DIO9	DIO8	O
FRAM Written	P5.5	DIO11	O	Reset	P7.3			Reset	I
Power radio	P1.4								
SPI MOSI	P6.4	DIO9							
SPI MISO	P6.5	DIO8							
SPI CLK	P6.6	DIO10							
SPI SS	P6.7	DIO20	O						

Note currently in our setup we have only one sniffer for two msp430 nodes. I/O are defined with respect to msp430 node  
Code needs update

**Figure 12:** Plan to Create Extra NC Pins on the CC1352R Development Board

# Stack Pinouts

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MSP Board Pinout								
Pin #	Func	Pin #	Func		Pin #	Func	Pin #	Func
1	3V3 to CC	21	3V3		40	P5.4	20	GND
2	GPIO	22	GND		39	GPIO	19	P5.1
3	GPIO	23	NC		38	P6.7	18	P5.5
4	GPIO	24	GPIO		37	P3.5	17	GPIO/EN
5	P5.0	25	GPIO		36	GPIO	16	NC
6	P5.2	26	GPIO		35	GPIO	15	P6.4
7	P6.6 (SPI)	27	GPIO		34	RST_MSP	14	P6.5
8	P1.0	28	P7.3		33	P1.1	13	P1.6
9	P7.4	29	P7.5		32	P1.7	12	P2.6
10	P7.6	30	P7.7		31	P2.5	11	GPIO

Figure 14: MSP Simplified Pinout

# Stack Pinouts

---

Harvester Board Pinout								
Pin #	Func	Pin #	Func		Pin #	Func	Pin #	Func
1	NC	21	3V3		40	P5.4	20	GND
2		22	GND		39		19	P5.1
3		23	NC		38	P6.7	18	P5.5
4		24			37	P3.5	17	
5	P5.0	25			36		16	NC
6	P5.2	26			35		15	P6.4
7	P6.6	27			34		14	P6.5
8	P1.0	28	P7.3		33	P1.1	13	P1.6
9	P7.4	29	P7.5		32	P1.7	12	P2.6
10	P7.6	30	P7.7		31	P2.5	11	

Figure 15: Power Harvester Pinout

## LIPO Cost Estimate (Slightly Outdated)

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Item	Cost per Item	Quantity	Total Cost
LIPO	\$5.00	10	\$50.00
Battery Mount	\$3.00	10	\$30.00
Protection/Management ICs	\$0.50	10	\$5.00
Charger ICs and parts	\$1.00	10	\$10.00
Charger PCB	\$15.00	1	\$15.00

Cost per board: \$11.00

Updated cost per board (no  
charging board): \$9.5

# Time Skew Analysis

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CC1352 clock was ran with constant time reporting, compared to real-time clock

Skew ended up  $> .005\%$ ,  $.01\%$  between any given 2 nodes

Two nodes skewing in opposite directions: take 50 seconds to skew by 5 ms

## Prototype Implementations - ????

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No Transmit	Min	Max	Mean
Power (mW)	4.6707	7.5945	5.9900
Current (mA)	1.4154	2.3014	1.8152

Transmit every 5ms	Min	Max	Mean
Power (mW)	4.6707	7.5945	5.9900
Current (mA)	1.4154	2.3014	1.8152

$$P_{avg} = 0.5(5.99) + 0.5(26.09) = 16.04mW$$

$$E_{wk} = P_{avg}(7)(24)(60)(60) = 9.701kJ$$

# Prototype Implementations - ????

No Transmit	Min	Max	Mean
Power (mW)	4.6707	7.5945	5.9900
Current (mA)	1.4154	2.3014	1.8152

Transmit every 5ms	Min	Max	Mean
Power (mW)	4.6707	7.5945	5.9900
Current (mA)	1.4154	2.3014	1.8152

$$capacity - needed = (0.5(I_{normal}) + 0.5(I_{trans,5ms}))(7)(24)$$

$$capacity - needed = ((0.5)(1.8152) + (0.5)(7.9060))(7)(24) = 816.581 mAh$$

$$capacity - needed = \left(\frac{P_{avg}}{V_{supplied}}\right)(7)(24) = \frac{2695}{V_{supplied}} mAh$$

+10% buffer

# References

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